LM331

AN-673 2-Way Multiplexed LCD Drive and Low Cost A/D-Converter Using V/F

Techniques with COP8 Microcontrollers



Literature Number: SNOA150

2-Way Multiplexed LCD Drive and Low Cost A/D Converter Using V/F Techniques with COP8 Microcontrollers

ABSTRACT

This application note is intended to show a general solution for implementing a low cost A/D and a 2-way multiplexed LCD drive using National Semiconductor's COP840C 8-bit microcontroller. The implementation is demonstrated by means of a digital personal scale. Details and function of the weight sensor itself are not covered in this note. Also the algorithms used to calculate the weight from the measured frequency are not included, as they are too specific and depend on the kind of sensor used.

Typical Applications

- Weighing scales
- Sensors with voltage output
- Capacitive or resistive sensors
- All kinds of measuring equipment
- Automotive test and control systems

Features

- 2-way multiplexed LCD drive capability up to 30 segments (4 digit and 2 dot points)
- Precision frequency measurement
- Low current consumption
- Current saving HALT mode
- Additional computing power for application specific tasks

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Itiplexed LCD Drive and Techniques with COP8

Microcontrollers

Low Cost A/D Converter

INTRODUCTION

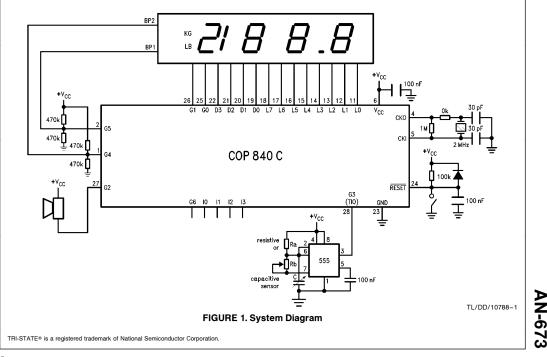
Today's most popular digital scales all have the following characteristics:

They are battery powered and use a LCD to display the weight. Instead of using a discrete A/D-converter, in many cases a V/F converter is used, which converts an output voltage change of the weight sensor to a frequency change. This frequency is measured by a microcontroller and is used to calculate the weight. The advantages of a V/F over an A/D converter are multifold. Only one line from the V/F to the microcontroller is needed, whereas a parallel A/D needs at least 8 lines or even more (National also offers A/Ds with serial output). A V/F can be constructed very simply using National Semiconductor's low cost, precision voltage to frequency converters LM331 or LM331A. Other possibilities are using Op-amps or a 555-timer in astable mode.

V/F-CONVERSION

Hardware

The basic configuration of the scale described in this application note is shown in *Figure 1*.



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A capacitive or resistive sensor's weight related capacitance or resistance change is transformed by a 555 timer (in astable mode) to a change of frequency. The output frequency f is determined by the formula:

The output high time is given by:

t1 = 0.693* (Ra + Rb) *C

The output low time is given by: $t2\,=\,0.693^*\,\textrm{Rb}^*\,\textrm{C}$

This frequency is measured using the COP800 16-bit timer in the "input capture" mode. After calculation, the weight is displayed on a 2-way multiplexed LCD. Using this configuration a complete scale can be built using only two ICs and a few external passive components.

For more information on V/F converters generally used with voltage output sensors, refer to the literature listed in the reference section.

Frequency Measurement

The COP 16-bit timer is ideally suited for precise frequency measurements with minimum software overhead. This timer has three programmable operating modes, of which the "input capture" mode is used for the frequency measurement. Allocated with the timer is a 16-bit "autoload/capture register". The G3-I/O-pin serves as the timer capture input (TIO). In the "input capture" mode the timer is decremented with the instruction cycle frequency (tc). Each positive going edge at TIO (also neg. edge programmable) causes the timer value to be copied automatically to the autoload/capture register without stopping the timer or destroying its

contents. The "timer pending" flag (TPND) in the PSW-register is set to indicate a capture has occurred, and if the timer-interrupt is enabled, an interrupt is generated. The frequency measurement routine listed below executes the following operations (refer to the RAM/register definition file listed at the beginning for symbolic names used in the routines):

The timer is preset with FFFF Hex and is started by setting the TRUN bit, after which the software checks the TPND-flag in a loop (timer interrupt is disabled). When the TPND flag is set the first time, the contents of the capture register is saved in RAM locations STALO and STAHI (start value). The TPND pending flag now must be reset by the software. Then, another 255 positive going edges are counted (equal to 255 pulses) before the capture register is saved in RAM locations ENDLO, ENDHI (end value). The shortest time period that can be measured depends on the number of instruction cycles needed to save the capture register, because with the next positive going edge on TIO the contents of the capture register is overwritten (worst case is 18 instruction cycles, which equals a max. frequency of 55.5 kHz at tc = 1 μ s).

The end-value is subtracted from the start-value and the result is restored in RAM locations STALO, STAHI. This value can then be used to calculate the time period of the frequency applied to TIO (G3) by multiplying it with the tc-time and dividing the result by the number of pulses measured (N = 255).

T = (startvalue - endvalue) *tc/N

;THE FOLLOWING "INCLUDE FILE" IS USED ;AS PART OF THE DEFINITION- AND INITIALIZATION PHASE ; IN COP800 PROGRAMS. ;REGISTER NAMES, CONTROL BITS ETC ARE NAMED IN THE ; SAME WAY IN THE COP800 DATA-SHEETS. --- COP800 MEMORY MAPPED ---; ; * PORT -, CONFIGURATION - AND CONTROL REGISTERS * ; ; ; L-PORT DATA REGISTER PORTLD 0D0 = PORTLC 0D1 ; L-PORT CONFIGURATION TL/DD/10788-2

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PORTLP 0D2 ; L-PORT INPUT REGISTER = PORTGD 0D4 ; G-PORT DATA REGISTER = PORTGC = 0D5 ; G-PORT CONFIGURATION ; G-PORT INPUT REGISTER 0D6 PORTGP = 0DC PORTD = ; D-PORT (OUTPUT) PORTI = 0D7 ; I-PORT (INPUT) SIOR 0E9 ; MWIRE SHIFT REGISTER = ; TIMER LOW-BYTE TMRLO = 0EA ; TIMER HIGH-BYTE ; T.-AUTO REG.LOW BYTE ; T.-AUTO REG.HIGH BYTE TMRHI = 0EB TAULO = 0EC TAUHI = 0ED 0ee CNTRL == ; CONTROL REGISTER PSW 0EF ; PSW-REGISTER = .FORM ; * CONSTANT DECLARE * ; ; --- CONTROL REGISTER BITS ---; S0 00 ; MICROWIRE CLOCK DIVIDE BY = --- BIT 0 ---; S1 01 MICROWIRE CLOCK DIVIDE BY = ; --- BIT 1 ---; ; EXTERNAL INTERRUPT EDGE 02 IEDG = ; POLARITY SELECT (0=RISING ; EDGE, 1=FALLING EDGE) ; ENABLE MICROWIRE FUNCTION MSEL 03 = --- SO AND SK ---; ; START/STOP THE TIM/COUNT. TRUN 04 = (1=RUN; 0=STOP); ; TIMER INPUT EDGE POL.SEL. TEDG 05 = ; (0=RIS. EDGE;1=FAL. EDGE) ; SELECTS THE CAPTURE MODE CSEL = 06 ; SELECTS THE TIMER MODE TSEL = 07 --- P S W REGISTER ---; GIE = 00 ; GLOBAL INTERRUPT ENABLE TL/DD/10788-3

01 ENT ; EXTERNAL INTERRUPT ENABLE = ; MICROWIRE BUSY SHIFTING BUSY = 02 IPND = 03 ; EXTERNAL INTERR. PENDING ENTI ; TIMER INTERRUPT ENABLE = 04 TPND = 05 ; TIMER INTERRUPT PENDING = ; CARRY FLAG C 06 ; HALF CARRY FLAG НC = 07 ;**** RAM-DEFINITIONS ***** BCDLO = 000 ; CALCULATED WEIGHT IN BCD ;LOW BYTE BCDHI = 001 ;CALCULATED WEIGHT IN BCD ;HIGH BYTE MWBUF0 = 003 ;7SEGMENT DATA FOR LCD DISPL ;L-PORT = 004 MWBUF1 ;D-PORT = 005 ;G-PORT MWBUF2 = 006 ; OFFSET REGISTERS FOR = 007 ;7 SEGMENT CODE TABLE OFF1 OFF2 OFF3 = 008 ; = 009 ;START VALUE,LOW BYTE = 00A ;START VALUE,HIGH BYTE STALO STAHI ENDLO = 00B ;END VALUE LOW BYTE ENDHI = 00C ;END VALUE HIGH BYTE DIV0 = 00D ;DIVISOR FOR DINBI248 ROUTINE ;022.. 02F RESERVED FOR STACK WITH COP820 ;062..06F RESERVED FOR STACK WITH COP840 ;**** REGISTER DEFINITIONS * * * * $\begin{array}{rcl} \text{COUNT} &=& 0 \text{F0} \\ \text{COUNT2} &=& 0 \text{F1} \end{array}$ COUNT3 = 0F2FLAG = 0FF;FLAG REGISTER ;**** BIT DEFINITIONS FLAG REGISTER **** POUND = 04; POUND=1: DISPLAY POUND SEGMENT ;POUND=0:DISPLAY kg SEGMENT ;***** G-PORT BIT DEFINITIONS ***** BP1 = 05 ;BACKPLANE 1 TL/DD/10788-4

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;TIME O	F 255 PU	JLSES, USING	TIMER INPUT CAPTURE MODE	
FMEAS:	LD LD LD LD	COUNT, #000 X, #TAULO B, #TMRLO [B+], #0FF [B], #0FF B, #CNTRL [B+], #0D0	<pre>;PERIOD TIME= ;(START-ENDVALUE)*tc/255 ;DIFFERENCE START-ENDVALUE ;IS STORED IN ENDLO,ENDHI ;LOAD PULSE COUNTER (255 PULSES) ;POINT TO AUTO REG. LOW B. ;PRESET TIMER ;REG. WITH FFFFh ;CNTRL-REG.: TIMER CAPTURE ;MODE,TIO POS. TRIGGERED, ;START TIMER</pre>	
L1:	RBIT IFBIT JP	#TPND, [B] #TPND, [B] SSTORE	;RESET TIMER PENDING FLAG	
SSTORE:	JP	L1	;STORE START VALUE	
	RBIT LD	#TPND, [B] A, [X+]	; LOAD TIMER CAPTURE REG.	
	X LD	A,STALO A,[X-]	;LOW BYTE ;STORE IN RAM ;LOAD HIGH BYTE CAPTURE, ;POINT TO LOW BYTE CAPTURE	
	X LD	A,STAHI B,#PSW	STORE IN RAM	
L256: DCOU:	IFBIT JP JP RBIT DRSZ JP	#TPND, [B] DCOU L256 #TPND, [B] COUNT L256	;RESET TIMER PENDING FLAG ;DECREMENT PULSE COUNTER ;COUNTER = 0 ? ;NO,LOOP 'TIL 255 PULSES ;HAVE BEEN MEASURED	
ESTORE:			;STORE END VALUE	
	LD LD LD X	CNTRL,#00 B,#STALO A,[X+] A,[B]	;STOP TIMER ;POINT TO START VALUE LOW BYTE ;LOAD END VALUE LOW BYTE ;LOAD ACCU WITH STARTVALUE LOW BYTE ;& STALO WITH END VALUE LOW BYTE	TL/DD/10788-5
	SC SUBC	A,[B]	;SUBTRACT ENDVALUE LOW BYTE	
	Х	A,[B+]	;FROM STARTVALUE LOW BYTE ;STORE RESULT IN STALO,	
	LD X	A,[X] A,[B]	; POINT TO STAHI ;LOAD ACCU WITH ENDVALUE HIGH BYTE ;LOAD ACCU WITH STARTVALUE HIGH BYTE ;& STAHI WITH ENDVALUE HIGH BYTE	
	SUBC	A, [B]	;SUBTRACT ENDVALUE HIGH BYTE FROM ;STARTVALUE HIGH BYTE	
	X RET .END	A,[B]	;STORE RESULT IN STAHL	TL/DD/10788-6

2-WAY MULTIPLEXED LCD DRIVE

Today a wide variety of LCDs, ranging from static to multiplex rates of 1:64 are available on the market. The multiplex rate of a LCD can be determined by the number of its backplanes (segment-common plate). The higher the multiplex rate the more individual segments can be controlled using only one line. e.g. a static LCD only has one backplane; only one segment can be controlled with one line. A two-way multiplexed LCD has two backplanes and two segments can be controlled with one line, etc.

Common to all LCDs is the fact that the drive voltage applied to the backplane(s) and segments has to be alternating. DC-components higher than 100 mV can cause electrochemical reactions (refer to manufacturer's spec), which reduce reliability and lifetime of the display.

If the multiplex ratio of the LCD is N and the amount of available outputs is M, the number of segments that can be driven is:

S = (M - N) * N

So the maximum number of a 2-way mux LCD's segments that can be driven with a COP800 in 28-pin package (if all outputs can be used to drive the LCD) is:

S = (18 - 2) * 2 = 32

During one LCD refresh cycle tx (typical values for 1/tx = fx are in the range 30 Hz ... 60 Hz), three different voltages levels: Vop, 0.5*Vop and 0V have to be generated. The "off" voltage across a segment is not 0V as with static LCDs and also the "on" voltage is not Vop, but only a fraction of it. The ratio of "on" to "off" r.m.s.-voltage (discrimination) is determined by the multiplex ratio and the number of voltage levels involved. The most desirable discrimination ratio is one that maximizes the ratio of V_{ON} to V_{OFF}, allowing the maximum voltage difference between activated and non-activated states. In general the maximum achievable ratio for any particular value of N is given by:

 (V_{ON}/V_{OFF}) max = SQR ((SQR(N) + 1)/(SQR(N) - 1))

SQR = square root

Using this formula the maximum achievable discrimination ratio for a 2-way multiplex LCD is 2.41, however, it is also possible to order a customized display with a smaller ratio. For ease of operation, most LCD drivers use equal voltage steps (0V, 0.5 *Vop, Vop). Thus a discrimination ratio of 2.24 is achieved. When using the COP800 to drive a 2-way multiplexed LCD the only external hardware required to achieve the three voltage steps are 4 equal resistors that form two voltage dividers—one for each backplane

(Figure 1). The procedure is to set G4 and G5 to "0" for 0V, to HI-Z (TRI-STATE®) for 0.5*Vop and to "1" in order to establish Vop at the backplane electrodes.

With the COP800 each I/O pin can be set individually to TRI-STATE, "1" or "0", so this procedure can be implemented very easily.

The current consumption of typical LCDs is in the range of 3 μ A to 4 μ A (at Vop = 4.5V, refresh rate 60 Hz) per square centimeter of activated area. Thus the backplane and segment terminals can be treated as Hi-Z loads. At high refresh rates the LCD's current consumption increases dramatically, which is the reason why many LCD manufacturers recommend not using a refresh frequency higher than 60 Hz. **Timing Considerations**

Timing Considerations

As shown in *Figures 2* and *3*, one LCD refresh cycle tx is subdivided into four equally distant time sections ta, tb, tc and td during which the backplane and segment terminals have to be updated in order to switch a specific segment on or off. Considering a refresh frequency of 50 Hz (tx = 20 ms) ta, tb, tc and td are equal to 5 ms; a COP800 running from an external clock of 2 MHz has an internal instruction cycle time of 5 μ s and a typical current consumption of less than 350 μ A (at V_{CC} = 3V and room temperature), thus meeting both the requirements of low current consumption and additional computing power between LCD refreshes.

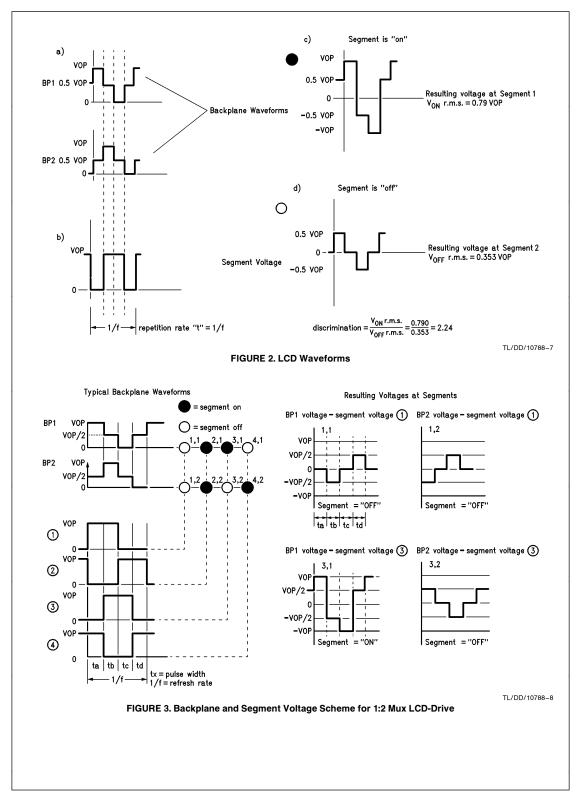
The timing is done using the COP800's 16-bit timer in the PWM autoload mode. The timer and the assigned 16-bit autoload register are preset with proper values. By setting the TRUN-flag in the CNTRL-register the timer is decremented each instruction cycle. A flag (TPND) is set at underflow and the timer is automatically reloaded with the value stored in the autoload-register. Timer underflow can also be programmed to generate an interrupt.

Segment Control

Figure 2 shows the voltage-waveforms applied to the two backplane-electrodes (a) and the waveform at a segementelectrode (b), which is needed to switch segment A on and segment B off. The resulting voltage over the segments (c and d) is achieved by subtracting waveform (b) from BP1 (segment A) and waveform (b) from BP2 (segment B).

Figure 3 shows the four different waveforms which must be generated to meet all possible combinations of two segments connected to the same driving terminal (off-off, on-off, off-on, on-on).

Figure 4 shows the internal segment and backplane connections for a typical 2-way mux LCD.



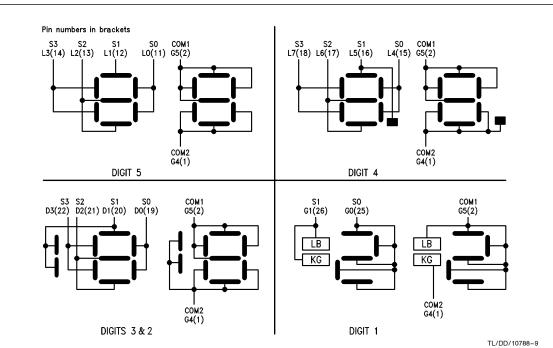


FIGURE 4. Customized LCD Display (Backplane and Segment Organization)

LCD Drive Subroutine

The LCD drive subroutine DISPL converts a 16-bit binary value to a 24-bit BCD-value for easier display data fetch. The drive subroutine itself is built up of a main routine doing the backplane refresh and 7 subroutines (SEG0, SEG1, SEG2, SEG3, SEGOUT, TTPND, DISPD). The subroutines SEG0 to SEG4 are used to get the LCD segment data from a look-up table in ROM for time phases ta, tb, tc and td respectively. Subroutine SEGOUT writes the segment data for each time phase to the corresponding output ports. One time phase takes 5 ms, giving a total refresh cycle time of 20 ms (50 Hz). The exact timing is done by using the COP800 16-bit timer in the PWM autoload mode. In that mode the timer is reloaded with the value stored in the autoload register on every timer underflow. At the same time the timer pending flag is set. The subroutine TTPND checks this flag in a loop. If the timer pending flag is set, this subroutine resets it and returns to the calling program. Thus a 5 ms time delay is created before the segment and backplane data for the next time phase is written to the output ports. Finally the subroutine DISPD switches off the LCD by setting the backplane and segment connections to "0". In this digital scale application a frequency measurement is made while the LCD is off. Then the weight is calculated from this frequency and is displayed for 10s. After this 10s the LCD is switched off again and the COP800 is programmed to enter the current saving HALT mode (I_{DD} < 10 μ A). A new weight cycle on the digital scale is initiated by pressing a push button, which causes a reset of the microcontroller.

CONCLUSIONS

National Semiconductor's COP800 Microcontroller family is ideally suited for use with V/F converters and 2-way multiplexed LCDs, as they offer features, which are essential for these types of applications. The high resolution, 3-mode programmable 16-bit timer allows precise frequency measurement in the input capture mode with minimum software overhead. The timer's PWM autoreload mode offers an easy way to implement a precise timebase for the LCD refresh. The COP800's programmable I/O ports provide flexibility in driving 2-way multiplexed LCDs directly. The COP800 family, fabricated using M2CMOS technology, offers both low voltage (min $V_{\rm CC}$ of 2.5V) and low current drain.

REFERENCES

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- U. Tietze, Ch. Schenk, "Halbleiter-Schaltungstechnik" 8.Auflage 1986, Springer Verlag, ISBN 0-387-16720-X, "Funktionsgeneratoren mit steuerbarer Frequenz", pages 465 ff, "Multivibratoren", pages 183 ff.
- 5. Lucid Displays, "LCD design guide", English Electric Valve Company Ltd., Chelmsford, Essex, Great Britain.

APPENDIX—Softwar	e Routines		
;LOOKUP TABL	E FOR CUSTOMIZED	2-WAY MULIPLEX LCD	
. = X'200 ;TIMEPHASE T .BYTE 004 .BYTE 008 .BYTE 008 .BYTE 008 .BYTE 002 .BYTE 001 .BYTE 001 .BYTE 001 .BYTE 000 .BYTE 000 .BYTE 000	a 7 SEGMENT DATA ;"0" AND ".0" ;"1" AND ".1" ;"2" AND ".2" ;"3" AND ".3" ;"4" AND ".4" ;"5" AND ".5" ;"6" AND ".6" ;"7" AND ".7"		
;SPECIAL SEG .BYTE 001 .BYTE 000 .BYTE 003 .BYTE 002	MENTS TIMPHASE Ta ;"LB" ;"LB 2" ;"KG" ;"KG 2"		
. = .+ 1	b 7 SEGMENT DATA ;"0" ;"1" ;"2" ;"3" ;"4"		TL/DD/10788-10

	. BYTE . BYTE	002 00A 00F 000 001 008 00C 008 00C 008 000 00C 000 00C 000 008 00D	; "8" ; "9" ; ".0" ; ".1" ; ".2" ; ".3" ; ".4" ; ".5" ; ".6" ; ".7" ; ".8" ; ".9"	
	.LOCAL			
TTPND:	LD	B,#PSW		
\$LOOP:	IFBIT JP JP	#TPND,[H \$END \$LOOP	3]	
\$END:	RBIT LD RET .LOCAL	#TPND,[E B,#PORTC		
	. = .+1 ;TIMEPH .BYTE .BYTE .BYTE .BYTE .BYTE .BYTE .BYTE .BYTE .BYTE .BYTE .BYTE	ASE TC 7 00B 001 007 00D 00E 00E 003 00F 00F 00F	SEGMENT DATA ;"0" AND ".0" ;"1" AND ".1" ;"2" AND ".2" ;"3" AND ".3" ;"4" AND ".4" ;"5" AND ".5" ;"6" AND ".5" ;"6" AND ".6" ;"7" AND ".7" ;"8" AND ".8" ;"9" AND ".9"	
COPY:			;COPY 2BYTES POINTED TO ;BY B AND B+1 TO RAM ;POINTED TO BY X AND X+1	
	LD X LD X RET .LOCAL	A, [B+] A, [X+] A, [B+] A, [X+]		
				TL/DD/10788-11

;TIMEPHASE Td 7 SEGMENT DATA ;"0" .BYTE 00D ;"1" 001 .BYTE ;"2" .BYTE 00C ;"3" .BYTE 005 ;"4" 001 .BYTE ;"5" .BYTE 005 ;"6" .BYTE 00D ;"7" .BYTE 001 ;"8" .BYTE 00D ;"9" 005 .BYTE ;" " .BYTE 000 ;".0" .BYTE 00F ;".1" .BYTE 003 ;".2" ;".3" .BYTE 00E .BYTE 007 ;".4" .BYTE 003 .BYTE 007 ;".5" ;".6" .BYTE 00F ;".7" 003 .BYTE ;".8" .BYTE 00F ;".9" 007 .BYTE .BYTE 002 ;". " ;SPECIAL SEGMENTS TIMEPHASE Tb .BYTE 003 ;"LB" .BYTE 003 ;"LB 2 " 001 001 ;"KG" ;"KG 2" .BYTE .BYTE ;"LB" ;"LB 2" ;"KG" ;"KC ;SPECIAL SEGMENTS TIMPHASE TC .BYTE 002 .BYTE 003 .BYTE 000 ;"KG 2" .BYTE 001 ;SPECIAL SEGMENTS TIMEPHASE Td ;"LB" ;"LB 2" .BYTE 000 000 .BYTE ; "KG" .BYTE 002 ;"KG 2" .BYTE 002 .END ;DISPL: ; INPUT PARAMETER: COUNT2 = RAM REGISTER, WHICH CONTAINS ; THE DISPLAY TIME IN SEC. ;EXAMPLE COUNT2= 1-> DISPLAY TIME IS 1SEC. ;LCD DRIVE ROUTINE FOR CUSTOMIZED 2 WAY MULTIPLEX ;LCD TL/DD/10788-12 ; ROUTINE CONVERTS BCD DATA STORED IN RAM LOCATIONS ;BCDLO, BCDHI INTO LCD OUTPUT DATA STORED AT ;MWBUF0 = LPORT DATA ;MWBUF1 = DPORT DATA ;MWBUF2 = G-PORT DATA (G0,G1 ONLY, OTHER BITS STAY UNCHANGED) ;SUBROUTINES INCLUDED: ;SEG0: GETS LCD SEGMENT DATA FOR TIMEPHASE TA ;SEG1: GETS LCD SEGMENT DATA FOR TIMEPHASE TB ;SEG2: GETS LCD SEGMENT DATA FOR TIMEPHASE TC ;SEG3: GETS LCD SEGMENT DATA FOR TIMEPHASE TD ; DISPD: SWITCHES THE DISPLAY OFF AND CONFIGURES G-, L- AND D-PORTS ;TTPND: CHECKS TIMER PENDING FLAG (REFRESH RATE GENERATION) ;SEGOUT: OUTPUTS LCD SEGMENT AND BACKPLANE DATA ;SUBROUTINES SEG0... SEG1 MUST FOLLOW DIRECTLY AFTER LOOK-UP ;TABLE, BECAUSE OF THE USE OF THE LAID-INSTRUCTION .LOCAL SEG0: LDB, #OFF1 ; POINT TO OFFSET 1 REG. [B+],#000 LD[B+],#000 LD LD A,#00B \$TWO: IFBIT #05, BCDHI ;WEIGHT >= 200 POUNDS? ;YES DISPLAY DIGIT5 ("2") INCA \$POUND: IFBIT #POUND, FLAG JP \$LPORT A,#002 ADD \$LPORT: Х A,[B] X, #BCDLO LD LD B,#MWBUF0 A,[X] LD AND A,#00F ;ELIMINATE DIGIT1 BITS ADD A,OFF2 ;GET DIGIT1 DATA LAID Х ;SAVE DIGIT1 DATA A,[B] ; IN MWBUF0 LD A,[X+] ;ELIMINATE DIGIT1 BITS AND A,#0F0 SWAP А ;ALWAYS DISPLAY DECIMAL POINT ADD A,OFF1 LAID ;GET DIGIT1 DATA SWAP А OR A,[B] ;STORE DIGIT1 AND Х A, [B+] ; DIGIT2 DATA IN MWBUF0 TL/DD/10788-13

\$DPORT:	LD IFBIT JP AND ADD	A,[X] #04,BCD \$ADD1 A,#00F A,OFF2	HI ;DISPLAY NO LEADING ZERO	
\$ADD1:	JP AND	\$GET A,#00F		
\$GET:	ADD	A, OFF1	;DISPLAY "1" (DIGIT4)	
A O D O D T	LAID X	A,[B+]	;GET DIGIT3 DATA ;STORE DIGIT3 DATA IN ;MWBUF1	
\$GPORT:	LD LAID	A,OFF3	;GET DIGIT5 ("2") AND SPECIAL	
0001	OR X RET	A,#0FC A,[B]	;SEGMENT DATA ;SET BITS 27 TO 1 ;SAVE DATA IN MWBUF2	
SEG1:	LD LD LD JP	B,#OFF1 [B+],#03 [B+],#03 A,#056 \$TWO	1B 10	
SEG2:	LD LD LD JP	B,#OFF1 [B+],#03 [B+],#03 A,#05A \$TWO		
SEG3:	LD LD LD JP .LOCAL	B,#OFF1 [B+],#0 [B+],#0 A,#05E \$TWO	4B 40	
DISPL:	IFBIT JP JD	#POUND, H MULT2	FLAG	
MULT2:	JP LD LD	LDT B,#BUF12 [B+],#22		TL/DD/10788-14

	LD JSR LD JSR LD LD JSR	X,#STALO MULBI168 B,#BUF12LC COPY STAHI+1,#C DIV0,#10 DIVBI248		
LDT:	JSR LD	BINBCD16 COUNT,#50	;CONVERT BINARY TO BCD WEIGHT ;REPEAT DISPLAY LOOP 50 TIMES ;(=1 SEC DISPLAY TIME)	
	LD LD LD LD LD	[B+] , #003	;LOAD TIMER WITH 1000(03E8h) ;(=50 Hz LCD REFRESH AT tc=5us) ;LOAD AUTOREG. WITH 1000	
	LD		;CNTRL-REG.:"TIMER WITH AUTO- ;LOAD"- MODE,START TIMER	
DISP1:	LD	[B+],#010	;PSW-REG.:RESET TPND FLAG	
	JSR	SEG0	;GET 7-SEGM. DATA FOR REFRESH ;TIMEPHASE Ta	
TP0:	JSR	TTPND	;TEST TIMER PENDING FLAG ;BACKPLANE REFRESH Ta	
	SBIT LD RBIT SBIT LD RBIT JSR JSR JSR	<pre>#BP1, [B] A, [B+] #BP2, [B] #BP1, [B] A, [B-] #BP2, [B] SEGOUT SEG1 TTPND</pre>	; POINT TO G-CONFIGREG. ; POINT TO G-DATA REG. ; SEGMENT DATA OUT ; GET 7-SEG. DATA FOR Tb	
TP1:	SBIT	#BP2,[B]		
	LD RBIT SBIT	#BP2,[B] #BP1,[B] #BP2,[B]	;POINT TO G-CONFREG.	
	LD RBIT	A,[B-] #BP1,[B]	;POINT TO G-DATA REG.	
	JSR JSR JSR	SEGOUT SEG2 TTPND	;GET 7-SEGM. DATA FOR TC	
TP2:	RBIT LD RBIT	#BP1,[B] A,[B+] #BP2,[B]	;POINT TO G-CONFIGREG.	
	SBIT LD RBIT JSR	#BP1,[B] A,[B-] #BP2,[B] SEGOUT	;POINT TO G-DATA-REG.	
				TL/DD/10788-15

		TOD	0000		
		JSR JSR	SEG3 TTPND		
	TP3:	RBIT RBIT LD RBIT SBIT JSR DRSZ	<pre>#BP1,[B] #BP2,[B] A,[B+] #BP1,[B] #BP2,[B] SEGOUT COUNT</pre>		
		JP LD	DISP1 COUNT,#50		
		DRSZ JP JSR	COUNT2 DISP1 DISPD	;10SEC OVER? ;NO, DISPLAY WEIGHT	
		RET	DISPD	;YES ROUTINE FINISHED	
	DISPD:			;SWITCH DISPLAY OFF	
		LD LD	B,#PORTLD [B+],#000	;OUTPUT 0 TO L PORT	
		LD LD	[B+],#0FF B,#PORTGD	;L-PORT = OUTPUT PORT	
		LD LD	[B+],#000 [B+],#037		
		LD RET	PORTD,#000) ;OUTPUT 0 TO D-PORT	
	SEGOUT:				
		LD LD X	B,#MWBUF0 A,[B+] A,PORTLD	;POINT TO MWBUF1 ;OUTPUT 7 SEG. DATA IN	
		LD	A,[B+]	;MWBUF0 TO L-PORT ;POINT TO MWBUF2	
		X LD	A, PORTD X, #PORTGD	;OUTPUT MWBUF1 TO D-PORT	
		LD AND	A, [X] A, [B]	;AND MWBUF2 WITH PORTGD	
		Х	A,[B]	;LEAVE BITS 27 UNCHANGED ;STORE RESULT (A')IN	
		AND	A,#003	;MWBUF2,LOAD A WITH ;ORIGINAL MWBUF2 VALUE ;AND 007 WITH ORIGINAL	
		AND	A,#003	;MWBUF2 (A''),SET BITS 0,1 TO ;CORRECT VALUE	
		OR	A,[B]	;OR A' WITH A'', RESTORE ORIGINAL ;G2G7 BITS	
		X RET	A,[X]	;OUTPUT RESULT TO G-PORT	
					TL/DD/10788-16
1					

;16 BIT BINARY TO BCD CONVERSION ;THE MEMORY ASSIGNMENTS ARE AS FOLLOWS: ;BINLO: RAM ADRESS BINARY LOW BYTE ;BCDLO: RAM ADRESS BCD LOW BYTE ;COUNT: RAM ADRESS SHIFT COUNTER (0F0...0FB,0FF) ; BCD NUMBER IN BCDLO, BCDLO+1, BCDLO+2 ; MEMORY ADRESS M(BINLO+1) M(BINLO) BINARY HB ;DATA BINARY LOW BYTE ; ; MEMORY ADRESS M(BCDLO+2) M(BCDLO+1) M(BCDLO) ;DATA BCD HB BCD BCD LOW BYTE ; BINLO = STALO .LOCAL \$BCDT = (BCDLO + 3) & OF\$BINT = (BINLO + 2) & OF BINBCD: COUNT, #16 ;LOAD CONTROL REGISTER WITH LD;NUMBER OF LEFTSHIFTS TO ;EXECUTE LD B, #BCDLO ;LOAD BCD-NUMBER LOWEST BYTE ;ADRESS ;CLEAR BCD RAM-REGISTERS \$CBCD: LD [B+],#00 IFBNE #\$BCDT JP \$CBCD ;LEFTSHIFT BINARY NUMBER \$LSH: LD B, #BINLO RC \$LSHFT: LD A,[B] A,[B] ADC ; IF MSB IS SET, SET CARRY Х A,[B+] IFBNE #\$BINT JP \$LSHFT B, #BCDLO LD\$BCDADD: LDA,[B] ;ADD CORRECTION FACTOR A,#066 ADD ADC A, [B] ;LEFTSHIFT BCD NUMBER ; (BCD=2**WEIGHT OF ;BINARY BIT (=CARRY BIT)) DCOR ; DECIMAL CORRECT ADDITION А A, [B+] Х IFBNE #\$BCDT TL/DD/10788-17 JP \$BCDADD DRSZ COUNT ;DECREMENT SHIFT COUNTER JP \$LSH RET .LOCAL TL/DD/10788-18

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;BINARY DIVIDE 24BIT BY 8BIT (Q=Y/Z)
;YL: LOW BYTE RAM ADRESS DIVIDEND
;ZL: LOW BYTE RAM ADRESS DIVISOR
;CNTR: RAM ADRESS SHIFT COUNTER (0F0...0FB,0FF)
;QUOTIENT AT RAM LOCATIONS YL..YL+2
;REMAINDER AT YL+3
;QUOTIENT IS ALL '1'S IF DIVIDE BY ZERO, REMAINDER
; THEN CONTAINS YL
; THE MEMORY ASSIGNMENTS ARE AS FOLLOWS:
;
        M(YH+1) M(YH)
                                M(YL+1) = M(YL)
;
                Y (HIGH BYTE) Y Y (LOW BYTE)
       0
;
       ___
                ---
                                         _____
;
        M(ZL)
;
        Ζ
;
;
;ROUTINE NEEDS 1.21ms FOR EXECUTION AT tc=1us
        ΖL
               = DIVO
              = STALO
= COUNT
        YL.
        CNTR
        .LOCAL
        $YH
               = YL+2
        $BTY
              = ($YH&00F)+2 ;PARAMETER FOR "IFBNE"-INSTR.
DIVBI248:
                CNTR, #018 ; INITIALIZE SHIFT COUNTER
        LD
                B,#$YH+1 ;FOR 24 COUNTS
[B],#000 ;PUT 0 IN M(YH+1)
        LD
        LD
                X,#$YH+1
        LD
$LSHFT:
        LD
               B, #YL ; LEFT SHIFT DIVIDEND
        RC
$LUP:
        LD
                A,[B]
        ADC
                A,[B]
                A, [B+]
        Х
        IFBNE
                #$BTY
        JP
                $LUP
        LD
                B,#ZL
        IFC
        JP
                $SUBT
$TSUBT:
                        ;SUBTRACT AND TEST
        SC
                        ;SUBTRACT Z FROM M(YH+1,YH+2)
        LD
                A,[X]
        SUBC
                A,[B]
        IFNC
        JP
                $TEST
                                                               TL/DD/10788-19
```

\$SUBT: ;SUBTRACT Z FROM M(YH+1, YH+2) LDA,[X] SUBC A,[B] Х A,[X] LD B,#YL SBIT #0,[B] \$TEST: CNTR ;24 SHIFTS EXECUTED? \$LSHFT ;NO, LEFT SHIFT DIVIDEND DRSZ CNTR JP RET .LOCAL ; BINARY MULTIPLIES A 16BIT VALUE (X1) ;WITH A 8BIT VALUE (X2): M = X1 + X2;X1L: RAM ADRESS X1 LOW BYTE ;X2L: RAM ADRESS X2 ;COUNT RAM ADRESS SHIFT COUNTER ;M IS STORED AT RAM ADRESSES X2L...X2L+2 ;THE MEMORY ASSIGNMENTS ARE AS FOLLOWS: ;MEMORY M(X2L+2) M(X2L+1) M(X2L) ;DATA 0 0 X2 ;-----; MEMORY M(X1L+1) M(X1L) X1 (LOW BYTE) X1(H.B.) ;DATA ;THE EXECUTION TIME FOR THE ROUTINE AT tc=lus IS 240us ; .LOCAL MULBI168: COUNT, #9 ; PRESET SHIFT COUNTER LD[B+],#00 ;PRESET X2L+1,X2L+2 WITH '0' LD[B]**,**#00 LDRC \$LOOP: A,[B] ;RIGHT SHIFT LDRRCA Х A,[B-] A,[B] LD RRCA Х A,[B-] LD A,[B] RRCA Х A,[B+] TL/DD/10788-20

\$TEST:	LD IFNC JP RC LD LD ADC X LD ADC X	A, [B+] \$TEST A, [B-] A, [X+] A, [B] A, [B+] A, [X-] A, [B] A, [B]	; INCREMENT B POINTER ; MOST SIGN. BIT OF X2 SET? ; NO, TEST SHIFT COUNTER ; YES, RESET CARRY ; POINT TO 2nd HIGHEST BYTE ; OF RESULT ; DO WEIGHTED ADD	
Ŷ1E51.	DRSZ JP RET .LOCAL .END	COUNT \$LOOP	;8 RIGHT SHIFTS EXECUTED? ;NO,SHIFT ;YES,MULIPLICATION FINISHED	TL/DD/10788-21

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